

Please amend the second complete paragraph beginning on page 9, line 11 as follows:

In an alternative embodiment, shown in Figure 9, there is no backing plate and the attachment mechanism is used with a circuit board 102 at least about two (2) cm thick, such as the type of circuit board used in the desktop manufacturing test environment or in a hard mount permanent desktop setting. The securing holes 914 for the locking pins 105 in this embodiment are provided in the circuit board 102 itself. In yet another embodiment, there are no through-holes on the circuit board, and any type of connecting means, such as hooks, screws, nuts and bolts, nails, and so forth, are used to secure the attachment mechanism to the processor.

IN THE CLAIMS

Please substitute the claim set in the appendix entitled Clean Version of Pending Claims for the previously pending claim set. The substitute claim set is intended to reflect amendment of previously pending claims 2, 6, 11, 19, 24, 25 and 29. The specific amendments to individual claims are detailed in the following marked up set of claims.

2. (Once Amended) The apparatus of claim 1 further comprising a backing plate connected to the mounting plate with the connector, wherein the second end of the connector is also securable to the backing plate, the backing plate designed to prevent flexure of the circuit board.

6. (Once Amended) The apparatus of claim 5 wherein the locking pins have bosses [sizeable] slidable along the shelves.

11. (Once Amended) The apparatus of claim 6 wherein the shelves are substantially angled and the thermal solution is [hard-mounted] permanently mounted to the mounting plate opening.

19. (Once Amended) A removable thermal solution attachment mechanism comprising:
a mounting plate having a mounting plate opening designed to allow the thermal solution to contact a processor located in [designed to mount a thermal solution to] a package;
a backing plate designed to connect to the mounting plate; and
connectors insertable into the mounting plate and backing plate wherein the thermal solution can impart a force on the package when the thermal solution is secured to the mounting plate, further wherein the thermal solution can remove heat from [a] the processor [located in the package].
24. (Once Amended) The mechanism of claim 19 wherein the backing plate and connectors are integrated into a bench top [fixtures] fixture.
25. (Once Amended) A method for attaching a thermal solution to a circuit board comprising:
placing a mounting plate on top of a [circuit board] processor, the processor located on a top surface of the circuit board and the mounting plate having a mounting plate opening designed to allow the thermal solution to contact a processor;
aligning slots on the mounting plate with locking pins securable to the circuit board;
inserting one end of each locking pin into each mounting plate slot;
sliding each locking pin along a shelf located in each mounting plate slot; and
securing a thermal solution to the mounting plate wherein pressure is applied to a package secured to the processor, the package located beneath the thermal solution.
29. (Once Amended) A method for temporarily attaching a thermal solution to a circuit board comprising:
providing a thermal solution attachment mechanism having first and second plates and a set of connectors to connect the first and second plates together;
placing a circuit board between the first and second plates wherein a thermal solution secured to an opening in the first plate contacts a package located on the circuit board;